CLAIMS

[Claim 1] A method for producing a semiconductor device, the method comprising:

preparing a dicing die-bonding integrated film, the dicing die-bonding integrated film including a base material layer, an adhesive layer formed from an active energy ray-curable adhesive, the adhesive layer having a first surface facing the base material layer and a second surface on the opposite side of the first surface, and a bonding adhesive layer provided so as to cover a central part of the second surface of the adhesive layer;

sticking a wafer to the bonding adhesive layer of the dicing die-bonding integrated film and sticking a dicing ring to the second surface of the adhesive layer;

singularizing the wafer, together with the bonding adhesive layer and the adhesive layer, into a plurality of chips by blade dicing using a blade to form cut bodies;

picking up each of the chips, together with an adhesive piece obtained by singularizing the bonding adhesive layer, from the adhesive layer of each of the cut bodies; and

mounting the chip on a substrate or another chip, with the adhesive piece interposed therebetween,

wherein the adhesive layer has a first region corresponding to a region in the bonding adhesive layer, to which the wafer is stuck, and a second region to which the dicing ring is stuck,

the first region is a region in a state of having an adhesive force decreased as compared with the second region by irradiation with active

energy rays, and

a kerf width formed in the adhesive layer of the cut body by the blade dicing is 75% or greater with respect to the width of the blade.

[Claim 2] The method for producing a semiconductor device according to claim 1,

wherein the width of the blade is 10 to 50 μm.

[Claim 3] The method for producing a semiconductor device according to claim 1 or 2,

wherein the plurality of chips have a square or rectangular shape, and each chip has an area of 200 mm^2 or less.

[Claim 4] The method for producing a semiconductor device according to any one of claims 1-3,

wherein the active energy ray-curable adhesive includes a (meth)acrylic resin having a functional group capable of chain polymerization,

the functional group is at least one selected from an acryloyl group and a methacryloyl group, and

the content of the functional group in the (meth)acrylic resin is 0.4 mmol/g or more.